

TI-PLABS-AMP-EVM

This user's guide describes the characteristics, operation, and use of the TI-PLABS-AMP-EVM evaluation board. It discusses how to set up the hardware, and reviews various aspects of the EVM operation. Throughout this document, the terms evaluation board, evaluation module, and EVM are synonymous with the TI-PLABS-AMP-EVM . This user's guide also includes information regarding operating procedures and input/output connections, an electrical schematic, printed circuit board (PCB) layout drawings, and a parts list for the EVM.

Contents

| | | |
|---|--|----|
| 1 | Overview | 2 |
| | 1.1 TI-PLABS-AMP-EVM Kit Contents | 2 |
| | 1.2 Related Documentation from Texas Instruments | 3 |
| 2 | External Connections | 4 |
| | 2.1 Inputs, Outputs, and Power | 4 |
| | 2.2 DIP Adaptors and Jumper Storage | 5 |
| 3 | Hardware Setup | 6 |
| | 3.1 Electrostatic Discharge Warning | 6 |
| | 3.2 Dip Adaptor Devices | 6 |
| | 3.3 Configuring a Circuit | 7 |
| | 3.4 Do Not Short the Outputs of Two Circuits | 7 |
| 4 | Schematic, PCB Layout, and Bill of Materials | 9 |
| | 4.1 Schematics | 9 |
| | 4.2 PCB Layout | 13 |
| | 4.3 TI-PLABS-AMP-EVM Bill of Materials | 14 |

List of Figures

| | | |
|----|--|----|
| 1 | Hardware included with TI-PLABS-AMP-EVM Kit | 2 |
| 2 | Input Output and Power Connections | 4 |
| 3 | DIP Adaptor and Jumper Storage | 5 |
| 4 | Removing the DIP Adaptor | 6 |
| 5 | Configuring a Circuit | 7 |
| 6 | Wrong Connection: Outputs are Shorted | 7 |
| 7 | Correct Connection: Outputs are Connected to Separate BNC Connectors | 8 |
| 8 | Circuit 1: Noninverting Amplifier | 9 |
| 9 | Circuit 2: Inverting Amplifier | 9 |
| 10 | Circuit 3: Cascaded Amplifier 1 | 10 |
| 11 | Circuit 4: Cascaded Amplifier 2 | 10 |
| 12 | Circuit 5: Riso Stability Circuit | 11 |
| 13 | Circuit 6: Riso Dual-Feedback Stability Circuit | 11 |
| 14 | Circuit 7: Multiple-Feedback LPF | 12 |
| 15 | Circuit 8: Sallen-Key LPF | 12 |
| 16 | PCB Components Layout | 13 |

1 Overview

The TI-PLABS-AMP-EVM is an experimentation board of op amp circuits. The EVM provides inverting-, noninverting-, cascaded-, and filter-amplifier configurations. The EVM is intended for use with the Precision Labs video series. The video series covers theory and laboratory experiments for different op amp subjects.

1.1 TI-PLABS-AMP-EVM Kit Contents

Table 1 details the contents of the TI-PLABS-AMP-EVM kit, and Figure 1 shows all of the included hardware. Contact the Texas Instruments Product Information Center at (972) 644-5580 if any component is missing.

Table 1. Contents of TI-PLABS-AMP-EVM Kit

| Item | Quantity |
|--------------------------------------|----------|
| TI-PLABS-AMP-EVM Test Board 1, Rev B | 1 |
| OPA211 DIP Adaptor | 2 |
| OPA188 DIP Adaptor | 2 |
| OPA171 DIP Adaptor | 1 |
| OPA277 DIP Adaptor | 1 |
| OPA140 DIP Adaptor | 1 |
| Jumper Shunts | 18 |

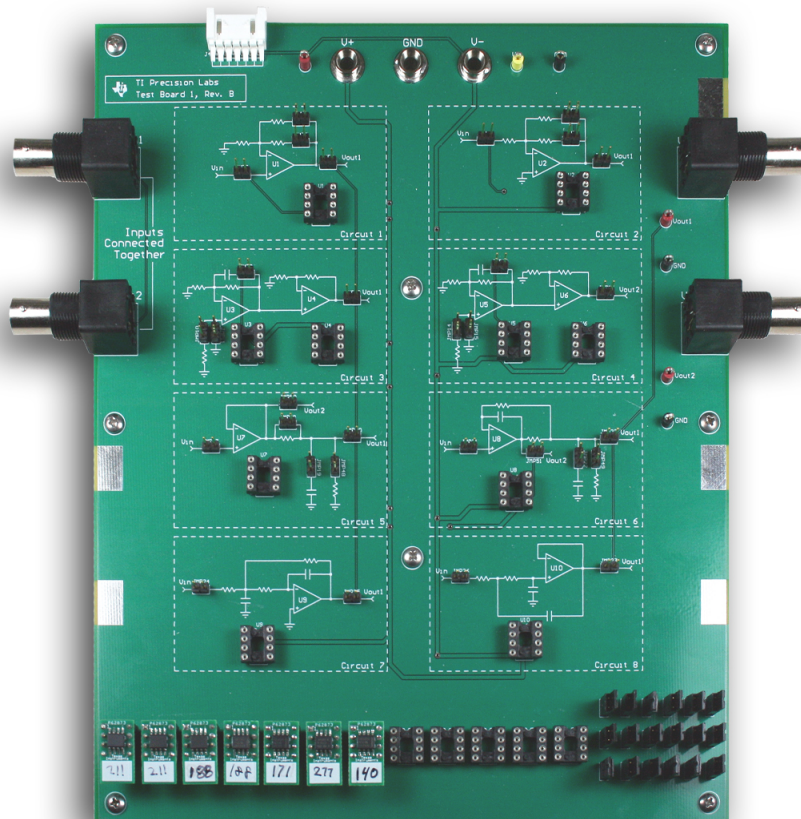


Figure 1. Hardware included with TI-PLABS-AMP-EVM Kit

1.2 Related Documentation from Texas Instruments

The following document provides information regarding Texas Instruments integrated circuits used in the assembly of the TI-PLABS-AMP-EVM. This user's guide is available from the TI web site under literature number [SBOU150](#). Any letter appended to the literature number corresponds to the document revision that is current at the time of the writing of this document. Newer revisions may be available from the TI web site at <http://www.ti.com/>, or call the Texas Instruments Literature Response Center at (800) 477-8924 or the Product Information Center at (972) 644-5580. When ordering, identify the document by both title and literature number

Table 2. Related Documentation

| Document | Literature Number |
|---|-------------------------|
| OPA211 Product Data Sheet | SBOS377 |
| OPA188 product data sheet | SBOS642 |
| OPA171 product data sheet | SBOS516 |
| OPA277 product data sheet | SBOS079 |
| OPA140 product data sheet | SBOS498 |

2 External Connections

2.1 Inputs, Outputs, and Power

Figure 2 shows the connections between the TI-PLABS-AMP-EVM and the test equipment. In this example, National Instruments' VirtualBench™ is used, but any standard test equipment can be used. Connect power to the EVM using connector J4 (Molex 6-pin power connector), or with three banana jacks (labeled V+, V-, and GND). The input connections are on the right-hand side of the board, and the output connections are on the left side. Note that the input connections are shorted together. One input connection is intended as a signal generator connection, and the other connection is used to monitor the input. The two output connections allow the comparison of two different circuits.

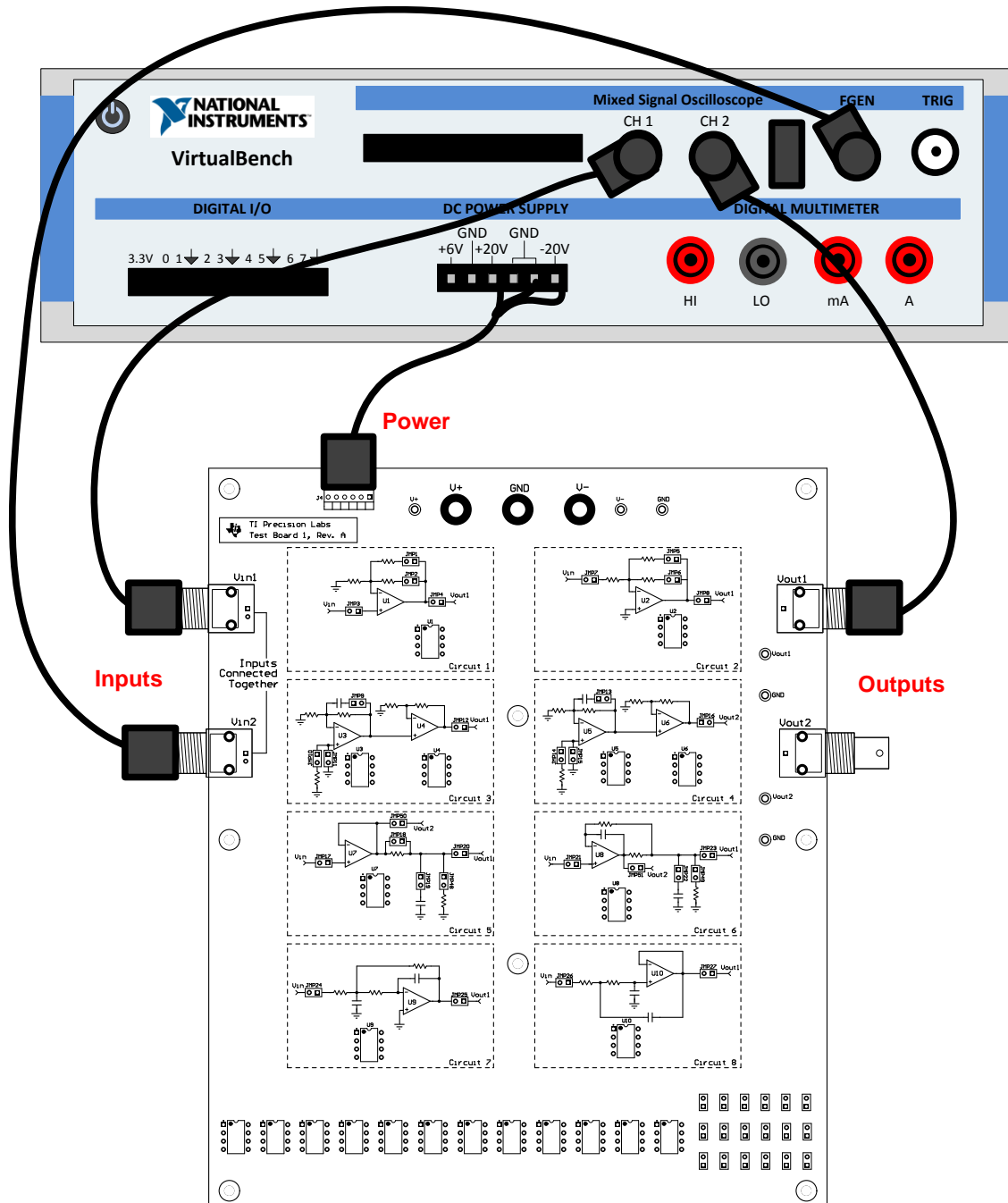


Figure 2. Input Output and Power Connections

2.2 DIP Adaptors and Jumper Storage

Figure 3 shows where the DIP adaptor devices and jumpers are stored on the TI-PLABS-AMP-EVM. Note that the DIP adaptor pins are grounded and no power is applied in this storage area. In general, populate only one experimentation circuit at a time. Make sure that all other circuits jumpers and DIP adaptors are removed and stored in the area identified in Figure 3. The only exception to this rule is that circuits 3 and 4 can both be populated at the same time so that the outputs can be compared.

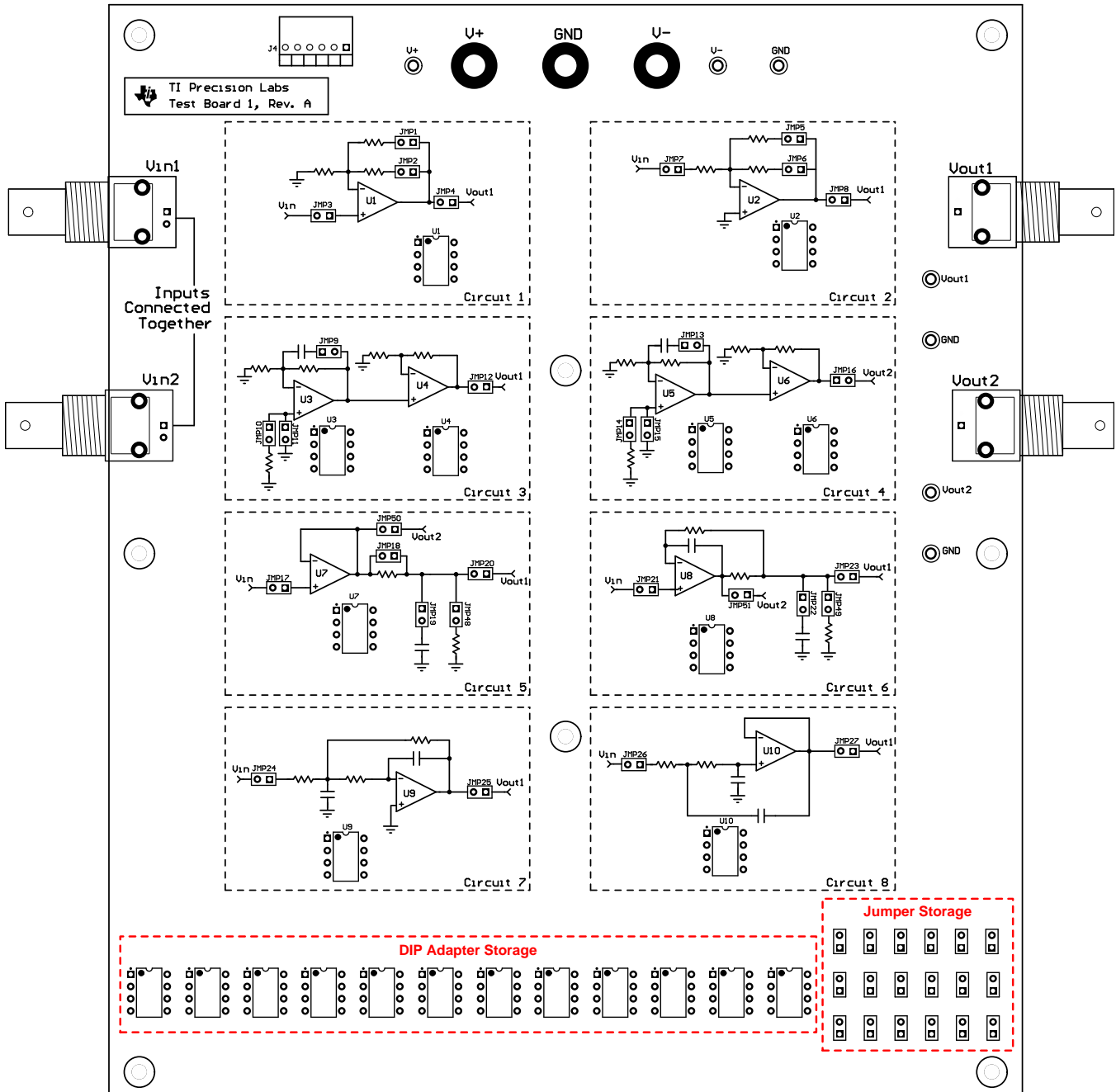


Figure 3. DIP Adaptor and Jumper Storage

3 Hardware Setup

The TI-PLABS-AMP-EVM hardware setup overview involves connecting the shunt and load resistor to the EVM, applying power, setting the jumpers, and measuring the output. This section presents the details of this procedure. The procedure given in each Precision Labs video provides additional information.

3.1 *Electrostatic Discharge Warning*

Many of the components on the TI-PLABS-AMP-EVM are susceptible to damage by electrostatic discharge (ESD).

CAUTION

Observe proper ESD handling precautions when unpacking and handling the EVM, including the use of a grounded wrist strap at an approved ESD workstation.

3.2 *Dip Adaptor Devices*

DIP adaptor cards containing different amplifier types are used for the experiments. Bent pins are a common problem that occurs when the adaptor cards are improperly removed from a socket. The proper way to remove the dip adaptor is to gently rock the card back and forth while pulling upward, as shown in [Figure 4](#).

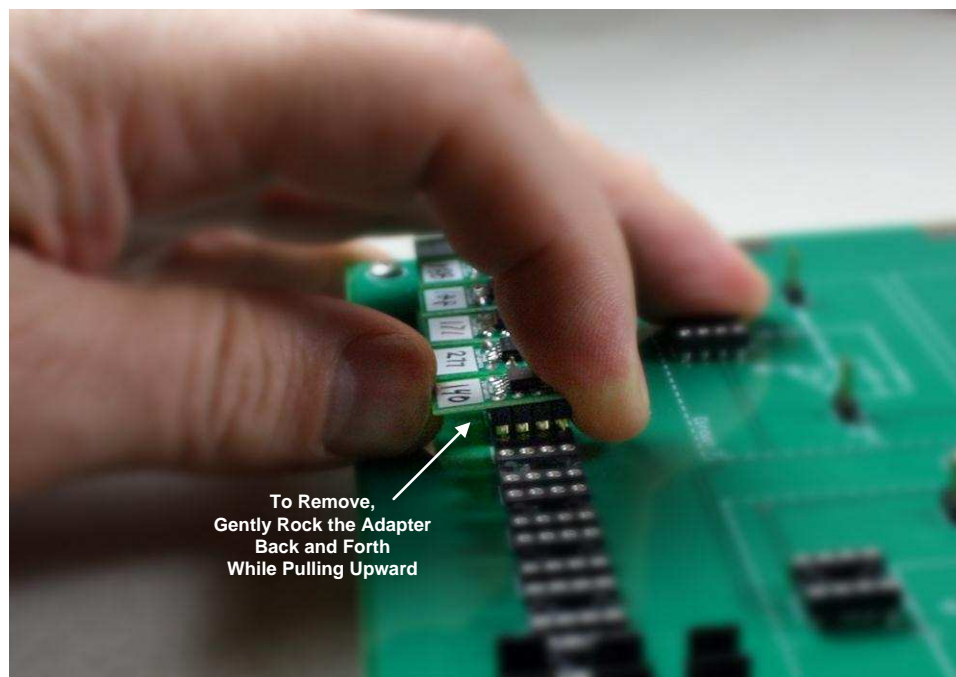


Figure 4. Removing the DIP Adaptor

3.3 Configuring a Circuit

Figure 5 shows an example of how a test circuit is configured. In this example, jumpers are used to connect the input, output, load resistance, and load capacitance. The dip adaptor card for the OPA140 is also installed. The Precision Labs videos give instructions on how the jumpers are configured and which amplifier is used.

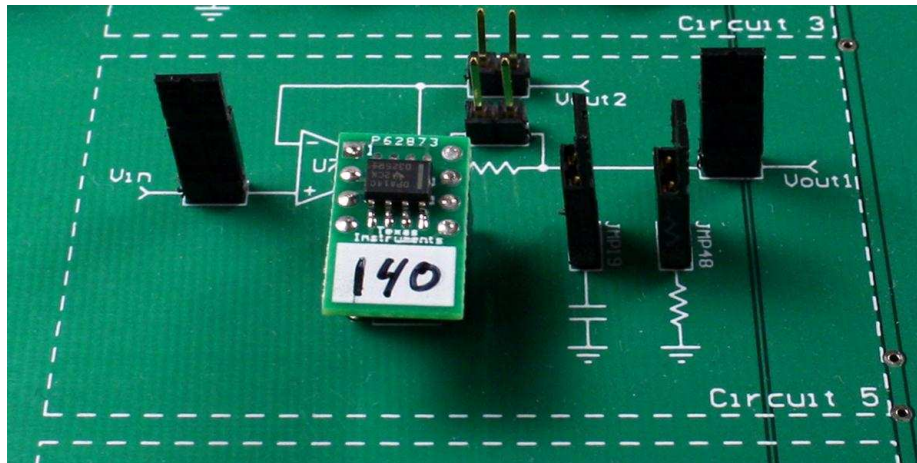


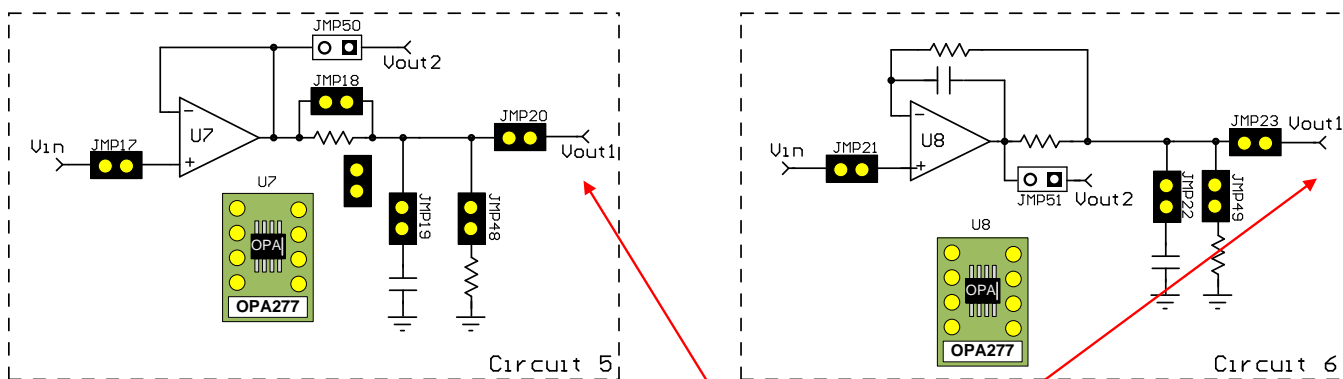
Figure 5. Configuring a Circuit

3.4 Do Not Short the Outputs of Two Circuits

For most experiments, only one test circuit is used at a time. Figure 6 shows a problem that occurs when populating two circuits simultaneously. In this example, both circuit 5 and circuit 6 are populated at the same time causing the outputs to short together.

CAUTION

This configuration produces erratic operation and may damage the circuits under test.



Do NOT populate two or more circuits with the same output simultaneously! In this case, the Vout1 outputs are shorted.

Figure 6. Wrong Connection: Outputs are Shorted

Figure 7 shows the only case where two circuits are populated simultaneously. In this case, both circuit 3 and circuit 4 are populated so that the two outputs are compared to each other. Note that in this case, the outputs are monitored on separate scope channels.

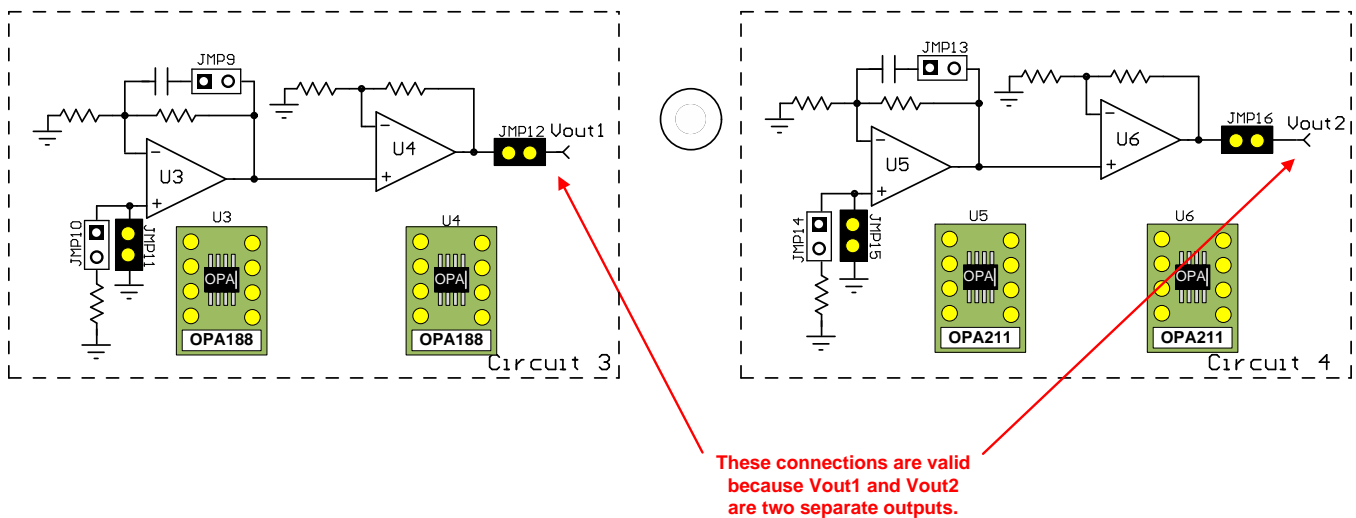


Figure 7. Correct Connection: Outputs are Connected to Separate BNC Connectors

4 Schematic, PCB Layout, and Bill of Materials

This section contains the complete bill of materials and schematic diagram for the TI-PLABS-AMP-EVM. Each schematic provides details explaining the operation of the circuit.

4.1 Schematics

4.1.1 Circuit 1: Noninverting Amplifier

Figure 8 shows the schematic for circuit 1, the noninverting amplifier. The gain of this circuit is 11 V/V when JMP2 is installed, and 101 V/V when JMP1 is installed. JMP3 and JMP4 connect the input and output to BNC connectors.

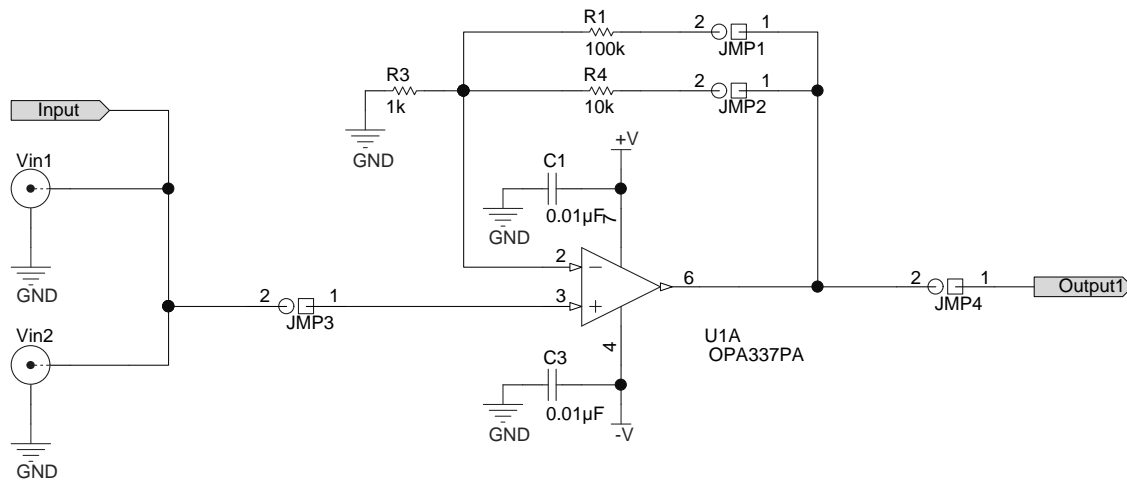


Figure 8. Circuit 1: Noninverting Amplifier

4.1.2 Circuit 2: Inverting Amplifier

Figure 9 shows the schematic for circuit 2, the inverting amplifier. The gain of this circuit is -20 V/V when JMP6 is installed, and -1 V/V when JMP5 is installed. JMP7 and JMP8 connect the input and output to BNC connectors.

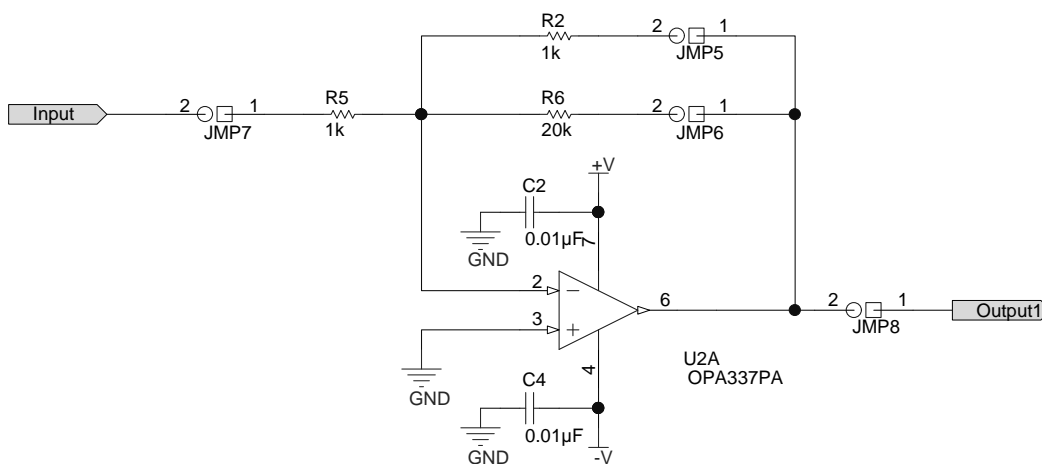


Figure 9. Circuit 2: Inverting Amplifier

4.1.3 Circuit 3 and Circuit 4: Cascaded Amplifiers

Figure 10 shows the schematic for circuit 3, cascaded amplifier 1. Figure 11 shows the schematic for circuit 4, cascaded amplifier 2. These circuits are used in noise and offset experiments because the high gain amplifies the noise and offset signal to a level that a standard scope or DMM can easily measure. The total gain for each circuit is 2121 V/V (gain = $101 \times 21 = 2121$). Circuit 3 and circuit 4 are identical so that the noise from two different amplifiers are compared. Note that the output of circuit 3 is connected to Vout1, and the output of circuit 4 is connected to Vout2.

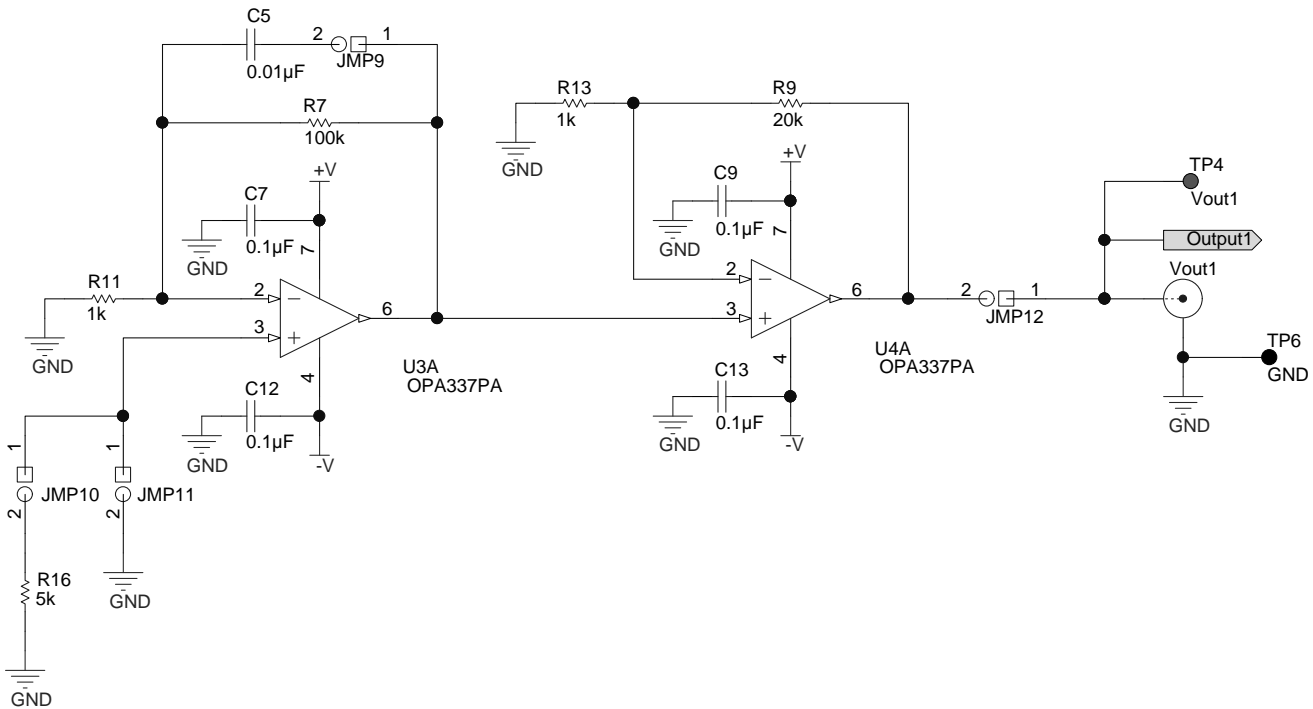


Figure 10. Circuit 3: Cascaded Amplifier 1

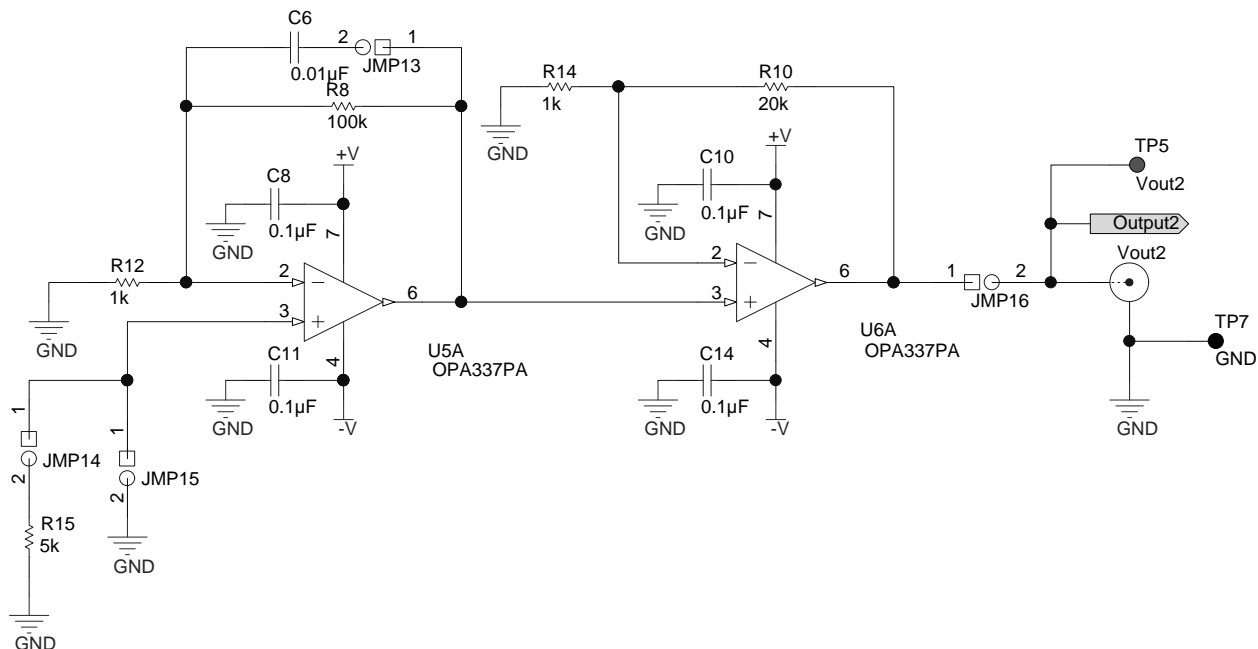


Figure 11. Circuit 4: Cascaded Amplifier 2

4.1.4 Circuit 5: Riso Stability Circuit

Figure 12 shows the schematic for circuit 5, the Riso stability circuit. This circuit shows how an isolation resistance is used to stabilize circuits with capacitive loads.

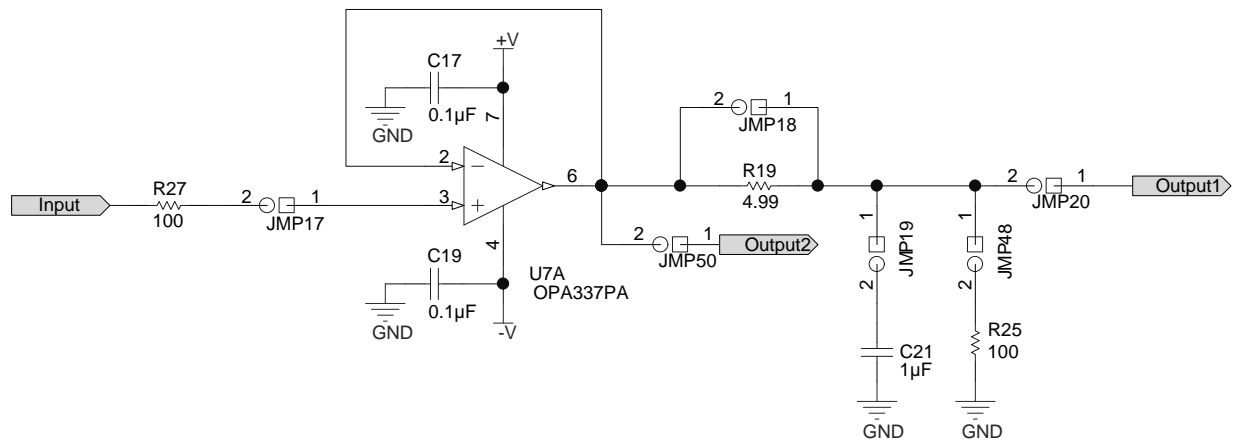


Figure 12. Circuit 5: Riso Stability Circuit

4.1.5 Circuit 6: Riso Dual-Feedback Stability Circuit

Figure 13 shows the schematic for circuit 6, the Riso dual-feedback stability circuit. This circuit shows how this circuit topology is used to stabilize circuits with capacitive load.

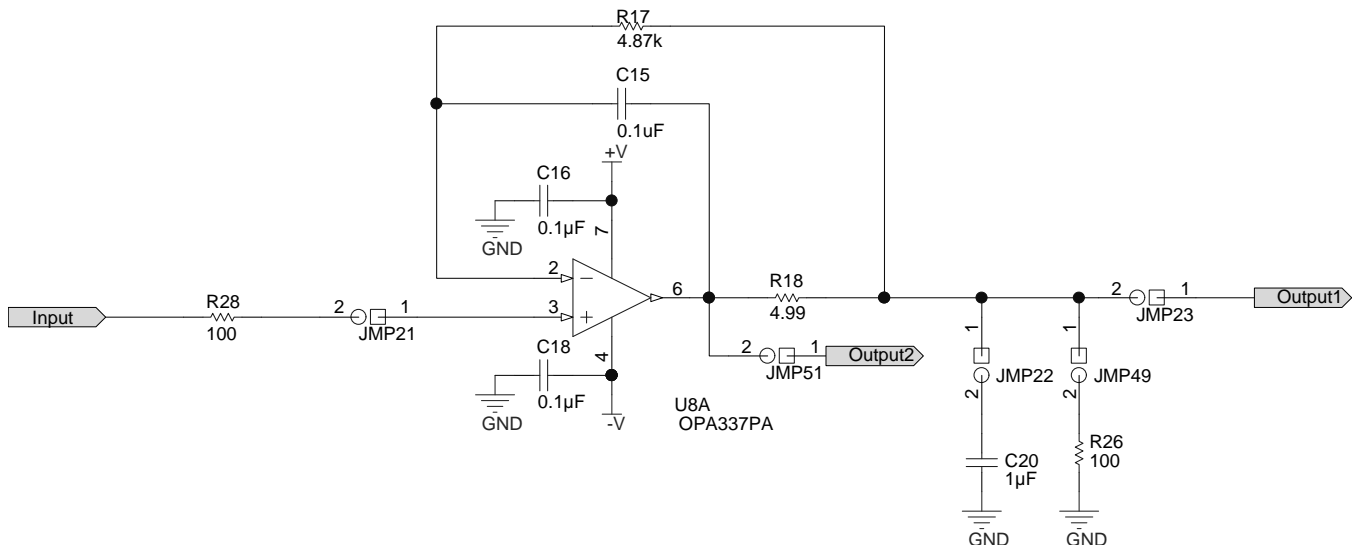


Figure 13. Circuit 6: Riso Dual-Feedback Stability Circuit

4.1.6 Circuit 7: Multiple-Feedback LPF

Figure 14 shows circuit 7, the multiple-feedback low-pass filter (LPF).

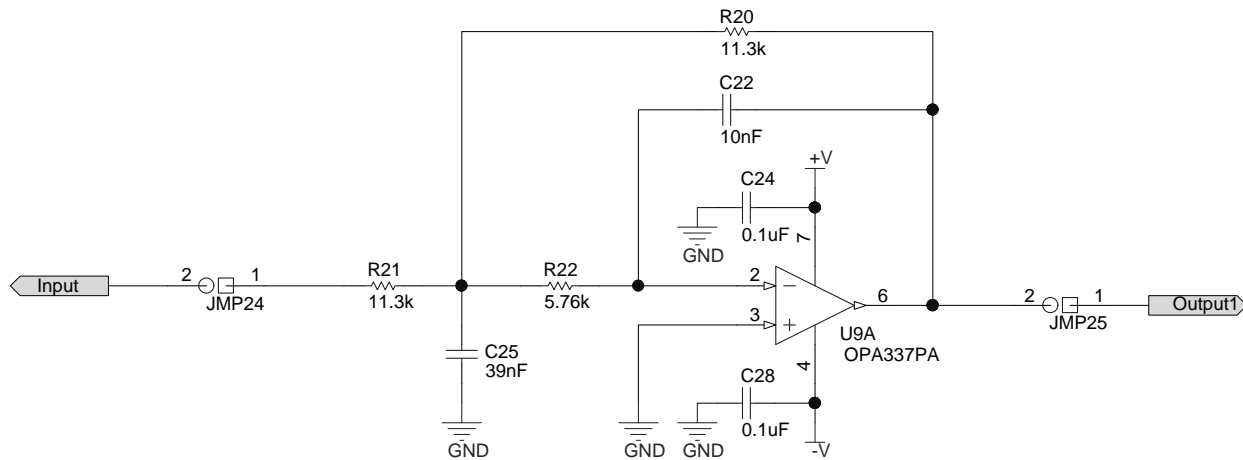


Figure 14. Circuit 7: Multiple-Feedback LPF

4.1.7 Circuit 8: Sallen-Key LPF

Figure 15 shows circuit 8, the Sallen-Key LPF.

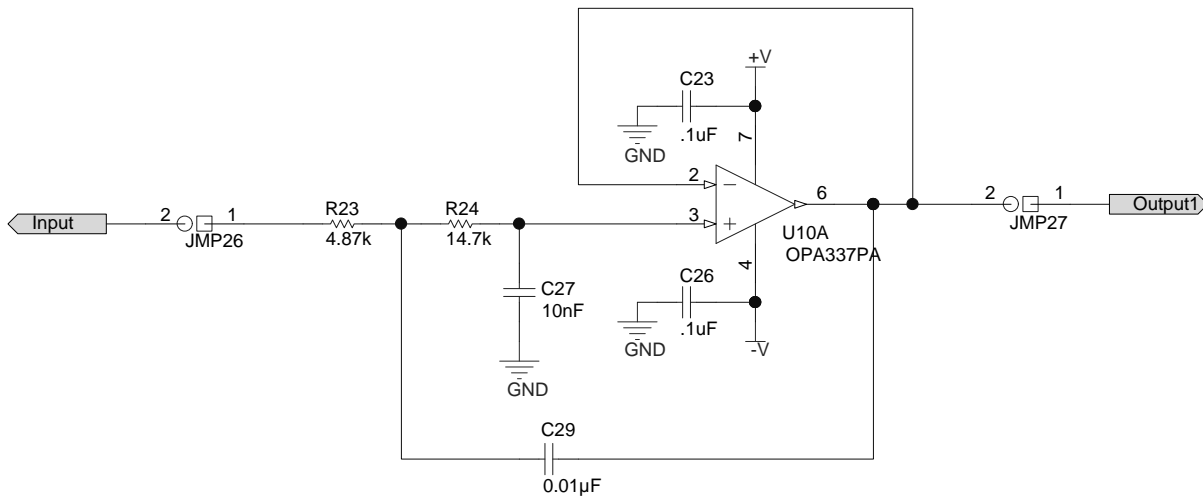


Figure 15. Circuit 8: Sallen-Key LPF

4.2 PCB Layout

Figure 16 shows the layout of the overview for the TI-PLABS-AMP-EVM board. The board is designed so that the silkscreen shows the schematic of the key sections of the board. Jumper placement is incorporated into the silk screen so that circuit configuration is intuitive.

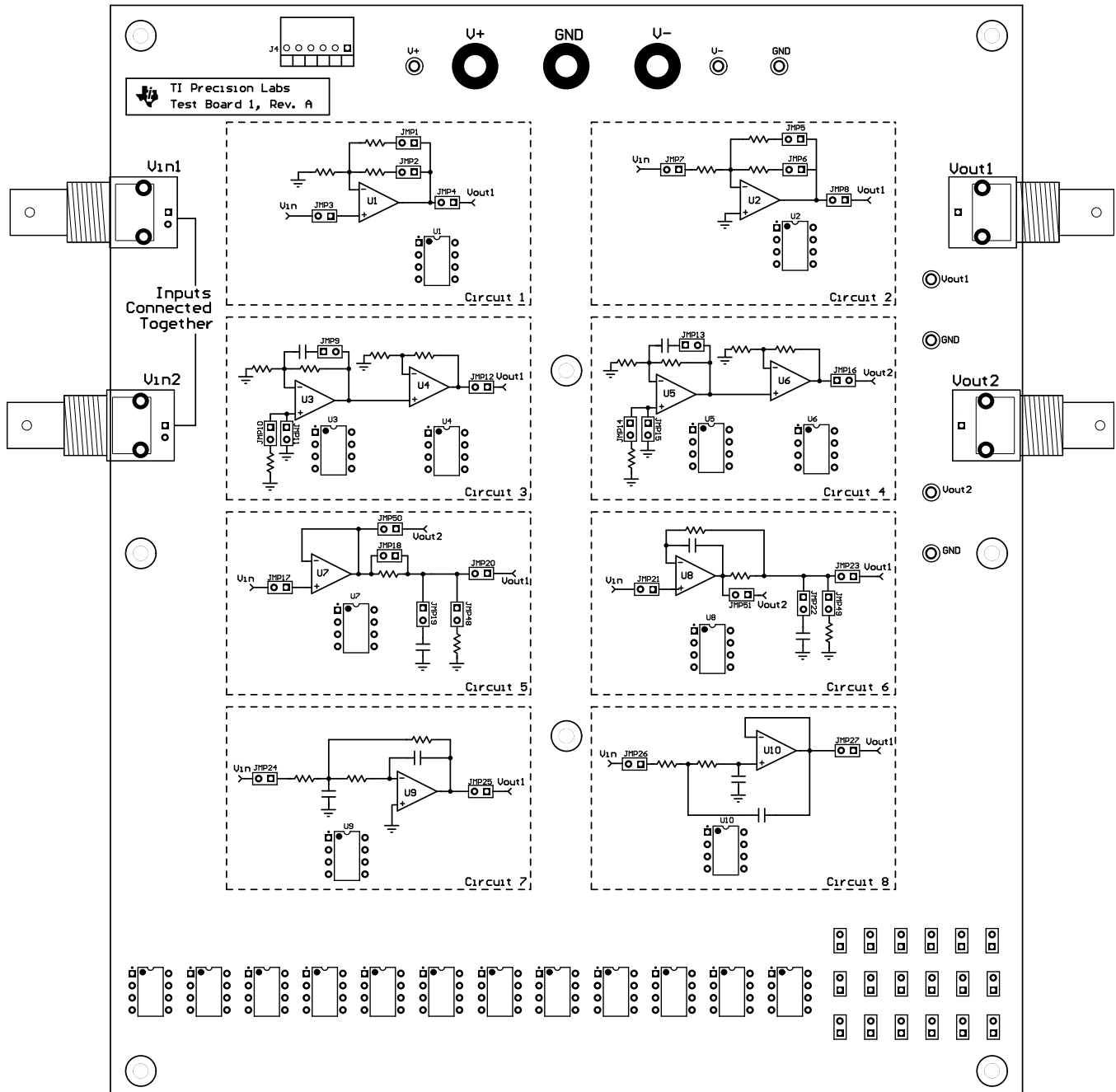


Figure 16. PCB Components Layout

4.3 TI-PLABS-AMP-EVM Bill of Materials

Table 3 lists the bill of materials for the TI-PLABS-AMP-EVM PCB.

Table 3. Bill of Materials

| Qty | Designator | Description | Manufacturer | Manufacturer Part Number | Digikey Part Number |
|-----|--|--|----------------------------------|--------------------------|---------------------|
| 2 | C20, C21 | 2.2nF | TDK Corporation | C2012C0G1H222J060AA | 445-7507-1-ND |
| 20 | C1–C4, C7–C14, C16–C19, C23, C24, C26, C28 | 0.1µF | Kemet | C0805C104K5RACTU | 399-1170-1-ND |
| 4 | C5, C6, C22, C27 | 1nF, CAP CER 1000PF 50V 5% NP0 0805 | Kemet | C0805C102J5GACTU | 399-1136-2-ND |
| 1 | C15 | 150pF | Kemet | C0805C151K5RACTU | 399-9176-1-ND |
| 2 | C30, C31 | CAP, TANT, 10µF, 20V, ±20%, 1 Ω, 3528-21 SMD | AVX | TPSB106M020R1000 | 478-4087-1-ND |
| 1 | C25 | 3.9nF, CAP CER 3900PF 50V 5% COG 0805 | TDK Corporation | C2012C0G1H392J060AA | 445-7510-2-ND |
| 1 | C29 | 2nF, CAP CER 2000PF 50V 5% NP0 0805 | Murata Electronics North America | GRM2165C1H202JA01D | 490-1627-1-ND |
| 2 | D1, D2 | Diode, TVS, Uni, 28V, 1500W, SMC | Diodes Inc | SMCJ28A-13-F | SMCJ28A-FDICT-ND |
| 3 | GND, V+, V- | Standard Banana Jack, Uninsulated, 5.5mm | Keystone | 575-4 | 575-4K-ND |
| 8 | H1–H8 | STANDOFF HEX 4-40THR ALUM 1/2 "L | Keystone | 2203 | 2203K-ND |
| 8 | H1–H8 | MACHINE SCREW PAN PHILLIPS 4-40 | B&F Fastener Supply | PMSSS 440 0025 PH | H703-ND |
| 1 | J4 | 2.5 WTB HEADER RA W/KINK 6CKT | Molex | 534260610 | WM3425-ND |
| 1 | J4-A | 2.5MM CRIMP HOUSING POS LOCK 6CI | Molex | 511030600 | WM9191-ND |
| 6 | J4-1–J4-6 | CONN TERM RCPT 22-28AWG CRIMP | Molex | 503518000 | WM3320CT-ND |
| 49 | Jumpers all | CONN HEADER 2POS 0.100" SGL GOLD | Samtec | TSW-102-07-G-S | SAM1029-02-ND |
| 9 | R2, R3, R5, R11–R14, R25, R26 | RES 1kΩ 1/8W 1% 0805 SMD | Yageo | RC0805FR-071KL | 311-1.00KCRCT-ND |
| 11 | R27–R37 | RES 100 Ω 1/8W 1% 0805 SMD | Yageo | RC0805FR-07100RL | 311-100CRCT-ND |
| 2 | R4, R38 | RES 10kΩ 1/8W 1% 0805 SMD | Yageo | RC0805FR-0710KL | 311-10.0KCRCT-ND |
| 3 | R6, R9, R10 | RES 20kΩ 1/8W 1% 0805 SMD | Yageo | RC0805FR-0720KL | 311-20.0KCRCT-ND |
| 3 | R1, R7, R8 | RES 100kΩ 1/8W 1% 0805 SMD | Yageo | RC0805FR-07100KL | 311-100KCRCT-ND |
| 2 | R15, R16 | RES 4.99kΩ 1/8W 1% 0805 SMD | Yageo | RC0805FR-074K99L | 311-4.99KCRCT-ND |
| 2 | R18, R19 | RES 787 Ω 1/8W 1% 0805 SMD | Yageo | RC0805FR-07787RL | 311-787CRCT-ND |
| 1 | R17 | RES 78.7kΩ 1/8W 1% 0805 SMD | Yageo | RC0805FR-0778K7L | 311-78.7KCRCT-ND |
| 4 | R20–R24 | RES 2.26kΩ 1/8W 1% 0805 SMD | Panasonic Electronic Components | ERJ-6ENF2261V | P2.26KCTR-ND |
| 1 | R22 | RES 1.13kΩ 1/8W 1% 0805 SMD | Panasonic Electronic Components | ERJ-6ENF1131V | P1.13KCCT-ND |
| 3 | TP1, TP4, TP5 | TEST POINT PC COMPACT 0.063"D RED | Keystone | 5005 | 5005K-ND |
| 3 | TP2, TP6, TP7 | TEST POINT PC COMPACT 0.063"D BLK | Keystone | 5006 | 5006K-ND |
| 1 | TP3 | TEST POINT PC COMPACT 0.063"D YLW | Keystone | 5009 | 5009K-ND |
| 22 | U1–U18, U21–U24 | IC SOCKET 8PIN MS TIN/TIN 0.300 | Mill-Max | 110-44-308-41-001000 | ED90048-ND |
| 4 | Vin1, Vin2, Vout1, Vout2 | CONN BNC JACK R/A 50 Ω PCB | TE Connectivity | 1-1634612-0 | A97555-ND |
| 20 | | Shunt, LP W/Handle 2 pos | TE Connectivity | 881545-2 | A26242-ND |
| 1 | N/A | HOOK-UP STRND 24AWG RED 100' | General Cable/Carol Brand | C2015A.12.03 | C2015R-100-ND |
| 1 | N/A | HOOK-UP STRND 24AWG BLACK 100' | General Cable/Carol Brand | C2015A.12.01 | C2015B-100-ND |
| 1 | N/A | HOOK-UP STRND 24AWG YELLOW 100' | General Cable/Carol Brand | C2015A.12.05 | C2015Y-100-ND |
| 7 | N/A | DIP Adapter boards, assembled and labeled as per DIP Adapter build files | N/A | N/A | N/A |
| 3 | N/A | Terminal Strip, 32 position | Samtec | TS-132-G-AA | N/A |
| 2 | N/A | IC, OPAMP 8-SOIC | Texas Instruments | OPA211AIDR | |
| 2 | N/A | IC, OPAMP 8-SOIC | Texas Instruments | OPA188AIDR | |
| 1 | N/A | IC, OPAMP 8-SOIC | Texas Instruments | OPA277UA | |

Revision History

| Changes from Original (January 2015) to A Revision | Page |
|--|------|
|--|------|

- Changed *Precision-Labs-EVM* to *TI-PLABS-AMP-EVM* throughout document..... 1
-

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

STANDARD TERMS AND CONDITIONS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, or documentation (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms and conditions set forth herein. Acceptance of the EVM is expressly subject to the following terms and conditions.
 - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms and conditions that accompany such Software
 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
 - 2.1 These terms and conditions do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
 - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for any defects that are caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI. Moreover, TI shall not be liable for any defects that result from User's design, specifications or instructions for such EVMs. Testing and other quality control techniques are used to the extent TI deems necessary or as mandated by government requirements. TI does not test all parameters of each EVM.
 - 2.3 If any EVM fails to conform to the warranty set forth above, TI's sole liability shall be at its option to repair or replace such EVM, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
 - 3.1 *United States*
 - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan are NOT certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】

本開発キットは技術基準適合証明を受けておりません。

本製品のご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。

日本テキサス・インスツルメンツ株式会社

東京都新宿区西新宿 6 丁目 2 4 番 1 号

西新宿三井ビル

3.3.3 *Notice for EVMs for Power Line Communication:* Please see http://www.tij.co.jp/llds/ti_ja/general/eStore/notice_02.page

電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。http://www.tij.co.jp/llds/ti_ja/general/eStore/notice_02.page

4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

6. *Disclaimers:*
- 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY WRITTEN DESIGN MATERIALS PROVIDED WITH THE EVM (AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
- 6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS AND CONDITIONS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT MADE, CONCEIVED OR ACQUIRED PRIOR TO OR AFTER DELIVERY OF THE EVM.
7. *USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.* USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS AND CONDITIONS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.
8. *Limitations on Damages and Liability:*
- 8.1 *General Limitations.* IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS AND CONDITIONS OR THE USE OF THE EVMS PROVIDED HEREUNDER, REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN ONE YEAR AFTER THE RELATED CAUSE OF ACTION HAS OCCURRED.
- 8.2 *Specific Limitations.* IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY WARRANTY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS AND CONDITIONS, OR ANY USE OF ANY TI EVM PROVIDED HEREUNDER, EXCEED THE TOTAL AMOUNT PAID TO TI FOR THE PARTICULAR UNITS SOLD UNDER THESE TERMS AND CONDITIONS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM AGAINST THE PARTICULAR UNITS SOLD TO USER UNDER THESE TERMS AND CONDITIONS SHALL NOT ENLARGE OR EXTEND THIS LIMIT.
9. *Return Policy.* Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.
10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2015, Texas Instruments Incorporated

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

| | |
|------------------------------|--|
| Audio | www.ti.com/audio |
| Amplifiers | amplifier.ti.com |
| Data Converters | dataconverter.ti.com |
| DLP® Products | www.dlp.com |
| DSP | dsp.ti.com |
| Clocks and Timers | www.ti.com/clocks |
| Interface | interface.ti.com |
| Logic | logic.ti.com |
| Power Mgmt | power.ti.com |
| Microcontrollers | microcontroller.ti.com |
| RFID | www.ti-rfid.com |
| OMAP Applications Processors | www.ti.com/omap |
| Wireless Connectivity | www.ti.com/wirelessconnectivity |

Applications

| | |
|-------------------------------|--|
| Automotive and Transportation | www.ti.com/automotive |
| Communications and Telecom | www.ti.com/communications |
| Computers and Peripherals | www.ti.com/computers |
| Consumer Electronics | www.ti.com/consumer-apps |
| Energy and Lighting | www.ti.com/energy |
| Industrial | www.ti.com/industrial |
| Medical | www.ti.com/medical |
| Security | www.ti.com/security |
| Space, Avionics and Defense | www.ti.com/space-avionics-defense |
| Video and Imaging | www.ti.com/video |

TI E2E Community

e2e.ti.com



**Стандарт
Электрон
Связь**

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,
Промышленная ул, дом № 19, литера Н,
помещение 100-Н Офис 331